

**40W - 28V - 500MHz**  
**GOLD METALLISED MULTI-PURPOSE**  
**SILICON DMOS RF FET**

**FEATURES**

- METAL GATE
- EXTRA LOW  $C_{rss}$
- BROAD BAND
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN

**APPLICATIONS**

- HF/VHF/UHF COMMUNICATIONS  
from DC to 850 MHz

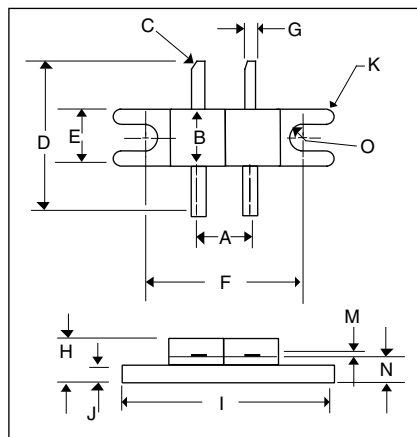
**ABSOLUTE MAXIMUM RATINGS**  
( $T_{CASE} = 25^{\circ}C$  unless otherwise stated)

$P_D$	Power Dissipation	175W
$BV_{DSS}$	Drain-source breakdown voltage	70V
$V_{GSS}$	Gate-source voltage	$\pm 20V$
$I_D$	Drain Current	10A
$T_{stg}$	Storage temperature	-65 to 150°C
$T_j$	Maximum operating junction temperature	200°C
$R_{THj-case}$	Thermal resistance junction-case	Max. 1.0°C/W

**ELECTRICAL CHARACTERISTICS** ( $T_{CASE} = 25^{\circ}C$  unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<u>PER SIDE</u>					
$BV_{DSS}$	Breakdown voltage, drain source $V_{GS}=0$ $I_D=100mA$	70			Vdc
$I_{DSS}$	Drain leakage current $V_{DS}=28V$ $V_{GS}=0$			2	mAdc
$I_{GSS}$	Gate leakage current $V_{GS}=20V$ $V_{DS}=0$			1	$\mu$ Adc
$V_{GS(th)}$	Gate threshold voltage $I_D=10mA$ $V_{DS}=V_{GS}$	1		7	Vdc
$g_{fs}$	Transconductance (300 $\mu$ s pulse) $V_{DS}=10V$ $I_D=2A$	1.6			Mhos
<u>TOTAL DEVICE</u>					
$G_{PS}$	Common source power gain $P_O=40W$	13			dB
$\eta$	Drain efficiency $V_{DS}=28V$ $I_{DQ}=0.8A$	50			%
VSWR	Load mismatch tolerance $f=500MHz$	20:1			
<u>PER SIDE</u>					
$C_{iss}$	Input capacitance $V_{DS}=0V$ $V_{GS}=-5V$ $f=1MHz$			120	pF
$C_{oss}$	Output capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			60	pF
$C_{rss}$	Reverse transfer capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			5	pF

**DIMENSIONS**

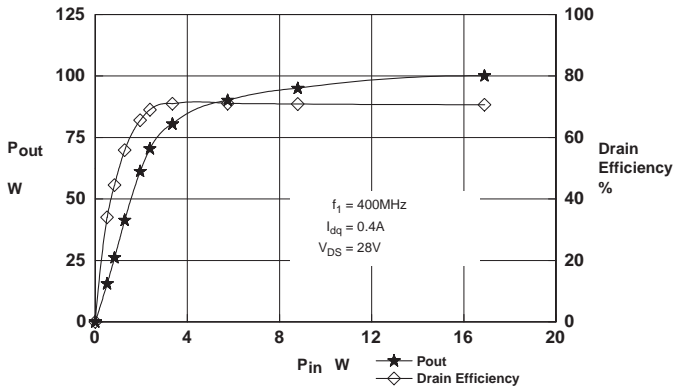


DM	Millimeter	TOL	Inches	TOL
A	6.45	.13	.254	.005
B	6.35	.13	.250	.005
C	45°	5°	45°	5°
D	16.51	.76	.650	.030
E	6.48	.13	.255	.005
F	18.42	.13	.725	.005
G	1.52	.13	.060	.005
H	4.83	.03	.160	.010
I	24.77	.13	.975	.005
J	1.52	.13	.060	.001
K	0.81R	.13	.032R	.005
M	.013	.02	.005	.001
N	2.16	.13	.085	.005
O	1.65R	.01	.065R	.005

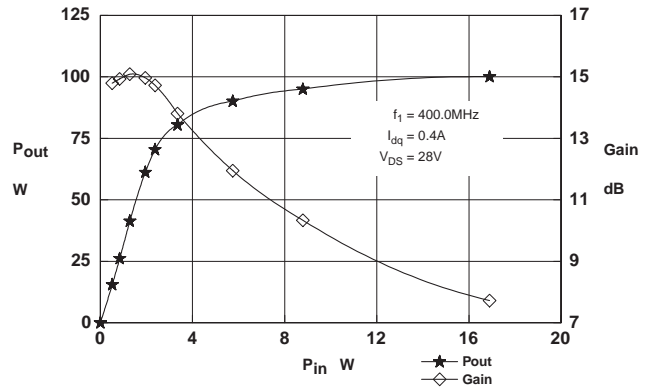
**HAZARDOUS MATERIAL WARNING**

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area. THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

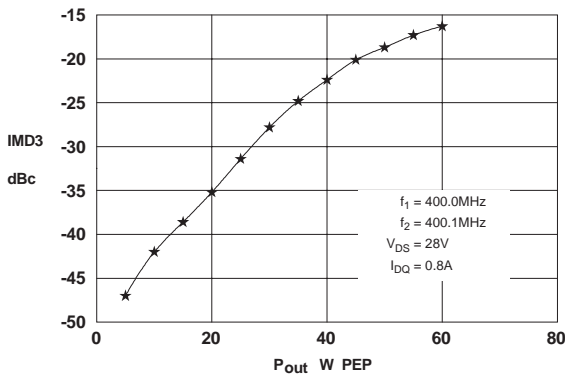
U.S. PATENTS 5,121,176 & 5,179,032  
GLOBAL PATENTS PENDING



**Figure 1 – Power Output and Efficiency vs. Power Input.**



**Figure 2 – Power Output & Gain vs. Power Input.**



**Figure 3 – IMD vs. Output Power.**

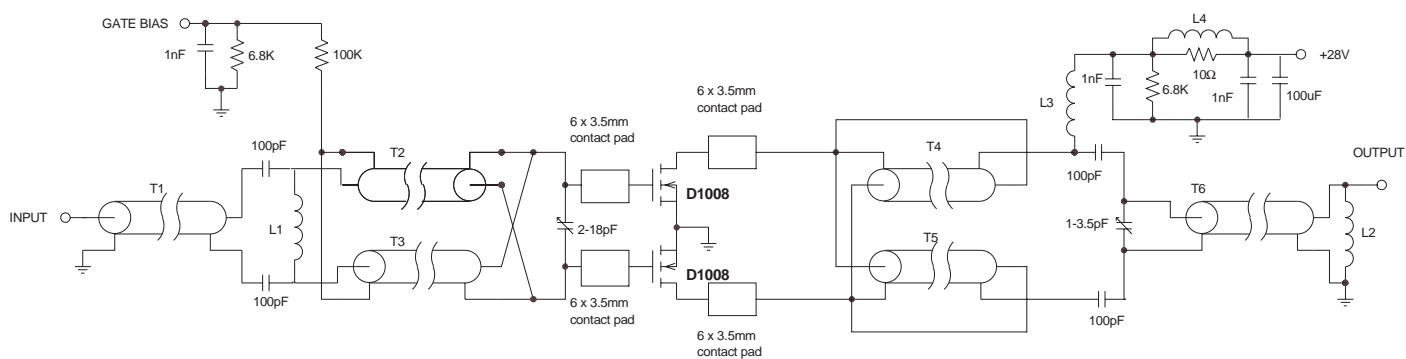
**D1008  
OPTIMUM SOURCE AND LOAD IMPEDANCE**

Frequency MHz	Z <sub>S</sub> Ω	Z <sub>L</sub> Ω
400	1.5 + j0.2	5.0 + j2.0

**Typical S Parameters**

! Vds=28V, Idq=1A  
# MHz S M A R 50

!Freq MHz	S11 mag ang	S21 mag ang	S12 mag ang	S22 mag ang
100	0.794 -158	14.622 69	0.0115 -7	0.61 -145
200	0.881 -167	5.821 42	0.0061 3	0.794 -156
300	0.923 -171	3.02 28	0.0068 60	0.871 -162
400	0.923 -176	1.82 18	0.117 77	0.902 -167
500	0.937 -179	1.439 15	0.0168 76	0.923 -169
600	0.952 177	1.057 13	0.0234 75	0.945 -171
700	0.966 174	0.676 10	0.0285 74	0.966 -174
800	0.966 171	0.543 5	0.0335 69	0.955 -177
900	0.977 167	0.447 1	0.0394 64	0.966 178
1000	0.966 165	0.359 1	0.0432 64	0.955 178



## D1008 TEST FIXTURE

Substrate 1.6mm PTFE/glass, Er=2.5  
All microstrip lines W=4.4mm

T1	70mm	50Ω	UT34	SEMI RIGID COAX	L1	3.5 turns of 24swg ECW, 3mm ID
T2,T3	85mm	25Ω	UT70-25	SEMI RIGID COAX	L2	5.5 turns of 24swg ECW, 4mm ID
T4,T5	100mm	15Ω	UT85-15	SEMI RIGID COAX	L3	4 turns of 21swg ECW, 7mm ID
T6	70mm	50Ω	UT85	SEMI RIGID COAX	L4	3 turns of 21swg ECW on Fair-Rite FT50-75 core

\*D1008 (per side)

\*PSPICE MODEL FOR POINT NINE TECHNOLOGIES, Inc RF N-CHANNEL VERTICAL DMOS POWER FET  
\*PRELIMINARY DATA, SEPTEMBER 1995

\*THIS IS A PUSH-PULL DEVICE, MODEL DATA IS PER SIDE  
\*TO GENERATE S PARAMETERS MATCHING DATA SHEET, SET VG=3.2V FOR IDQ=1A

```
*      ____GATE
*      I      ____DRAIN
*      I      I      ____SOURCE
*      I      I      I
.SUBCKT D1008 10 20 30
LG 10 11 1.85N
RGATE 11 12 0.39
CG 10 30 0.05P
CRSS 12 17 5P
CISS 12 14 120P
LS 14 30 0.15N
CS 14 30 0.1P
LD 17 20 0.42N
CD 20 30 1.44P
R_RC 16 17 35.73
C_RC 14 16 11.8P
MOS 13 12 14 15 D1008MOS L=0.71U W=0.112664 ;D G S B LEVEL1
JFET 17 14 13 D1008JF ;D G S
DBODY 14 17 D1008DB ;P N

.MODEL D1008MOS NMOS (VTO=2.2 KP=1.8E-5 LAMBDA=0.1 RD=0.13 RS=0.25)
.MODEL D1008JF NJF (VTO=-7.5 BETA=0.04 LAMBDA=1)
.MODEL D1008DB D (CJO=177P RS=0.25 VJ=0.7 M=0.33 BV=70)
.ENDS
```

D1008.s2p (each side)

```
!      Vds=28V, Idq=1A
#      MHz S MA R 50
```

!Freq	S11		S21		S12		S22	
!MHz	mag	ang	mag	ang	mag	ang	mag	ang
100	0.794	-158	14.622	69	0.0115	-7	0.61	-145
200	0.881	-167	5.821	42	0.0061	3	0.794	-156
300	0.923	-171	3.02	28	0.0068	60	0.871	-162
400	0.923	-176	1.82	18	0.117	77	0.902	-167
500	0.937	-179	1.439	15	0.0168	76	0.923	-169
600	0.952	177	1.057	13	0.0234	75	0.945	-171
700	0.966	174	0.676	10	0.0285	74	0.966	-174
800	0.966	171	0.543	5	0.0335	69	0.955	-177
900	0.977	167	0.447	1	0.0394	64	0.966	178
1000	0.966	165	0.359	1	0.0432	64	0.955	178